

MOS FET WITH SCHOTTKY BARRIER DIODE μ PA1980

P-CHANNEL MOS FET WITH SCHOTTKY BARRIER DIODE FOR SWITCHING

DESCRIPTION

The μ PA1980 is a switching device, which can be driven directly by a 1.8 V power source.

This device incorporates a MOS FET, which features a low on-state resistance and excellent switching characteristics, and a low leakage Schottky barrier diode, and is suitable for applications such as DC/DC converter of portable machine and so on.

FEATURES

- 1.8 V drive available (MOS FET)
- Low on-state resistance (MOS FET)

RDS(on)1 = 135 m Ω MAX. (VGS = -4.5 V, ID = -1.0 A)

 $R_{DS(on)2} = 183 \text{ m}\Omega \text{ MAX.} \text{ (Vgs} = -2.5 \text{ V, Ip} = -1.0 \text{ A)}$

 $R_{DS(on)3} = 284 \text{ m}\Omega \text{ MAX.} (V_{GS} = -1.8 \text{ V}, I_{D} = -0.5 \text{ A})$

• Low reverse current (Schottky barrier diode)

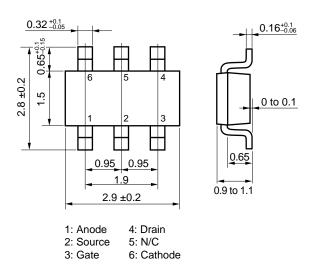
 $I_R = 20 \mu A MAX. (V_R = 40 V)$

ORDERING INFORMATION

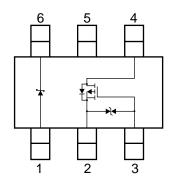
PART NUMBER	PACKAGE			
μ PA1980TE	SC-95 (Mini Mold Thin Type)			

Marking: TW

PACKAGE DRAWING (Unit: mm)



PIN CONNECTION (Top View)



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD.

When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

Caution This product is electrostatic-sensitive device due to low ESD capability and should be handled with caution for electrostatic discharge.

VESD \pm 100 V TYP. (C = 200 pF, R = 0 Ω , Single pulse)

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MOS FET ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Drain to Source Voltage (Vgs = 0 V)	VDSS	-20.0	V
Gate to Source Voltage (Vps = 0 V)	Vgss	∓8.0	V
Drain Current (DC)	I _{D(DC)}	∓2.0	Α
Drain Current (pulse) Note1	ID(pulse)	∓8.0	Α
Total Power Dissipation Note2	Рт	0.57	W
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	-55 to +125	°C

Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1%

2. Mounted on FR-4 board of 5000 mm² x 1.1 mm, $t \le 5$ sec.

SCHOTTKY BARRIER DIODE ABSOLUTE MAXIMUM RATINGS (TA = 25°C)

Repetitive Peak Reverse Voltage	V_{RRM}	40	V
Average Forward Current Note3	I F(AV)	0.5	Α
Surge Current Note4	IFSM	5.5	Α
Junction Temperature	T_j	+125	°C
Storage Temperature	T _{stg}	-55 to +125	°C

Notes 3. Mounted on FR-4 board of 5000 mm² x 1.1 mm

4. 50 Hz sine wave, 1 cycle

MOS FET ELECTRICAL CHARACTERISTICS (TA = 25°C)

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	loss	V _{DS} = -20.0 V, V _{GS} = 0 V			-10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \mp 8.0 \text{ V}, V_{DS} = 0 \text{ V}$			∓10	μΑ
Gate Cut-off Voltage Note	V _{GS(off)}	V _{DS} = -10.0 V, I _D = -1.0 mA	-0.45	-0.75	-1.50	V
Forward Transfer Admittance Note	y _{fs}	V _{DS} = -10.0 V, I _D = -1.0 A	1.0	4.1		S
Drain to Source On-state Resistance Note	R _{DS(on)1}	Vgs = -4.5 V, ID = -1.0 A		116	135	mΩ
	RDS(on)2	Vgs = -2.5 V, ID = -1.0 A		142	183	mΩ
	RDS(on)3	Vgs = -1.8 V, ID = -0.5 A		170	284	mΩ
Input Capacitance	Ciss	V _{DS} = -10.0 V		272		pF
Output Capacitance	Coss	V _G S = 0 V		60		pF
Reverse Transfer Capacitance	Crss	f = 1.0 MHz		30		pF
Turn-on Delay Time	td(on)	V _{DD} = -10.0 V, I _D = -1.0 A		9		ns
Rise Time	tr	V _{GS} = -4.0 V		5		ns
Turn-off Delay Time	td(off)	R _G = 10 Ω		33		ns
Fall Time	tf			9		ns
Total Gate Charge	Q _G	V _{DD} = -16.0 V		2.3		nC
Gate to Source Charge	Q _{GS}	Vgs = -4.0 V		0.6		nC
Gate to Drain Charge	Q _{GD}	Ib = -2.0 A		0.6		nC
Body Diode Forward Voltage	V _{F(S-D)}	IF = 2.0 A, VGS = 0 V		0.90		V

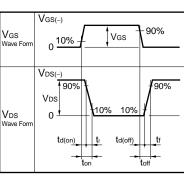
Note Pulsed: PW \leq 350 μ s, Duty Cycle \leq 2%

SCHOTTKY BARRIER DIODE ELECTRICAL CHARACTERISTICS (TA = 25°C)

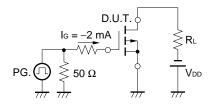
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CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Forward Voltage	VF	I _F = 0.5 A		0.44	0.51	٧
Reverse Current	IR	V _R = 40.0 V		3	20	μΑ

TEST CIRCUIT 1 SWITCHING TIME

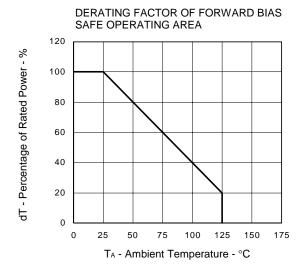
PG. \square R_{G} $V_{GS(-)}$ 0 $\tau = 1 \mu s$ Duty Cycle $\leq 1\%$

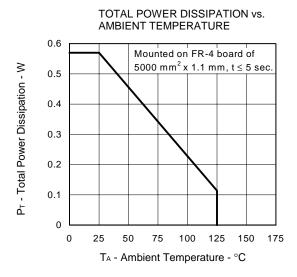


TEST CIRCUIT 2 GATE CHARGE

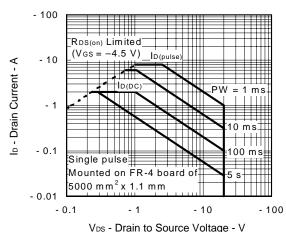


MOS FET TYPICAL CHARACTERISTICS (TA = 25°C)

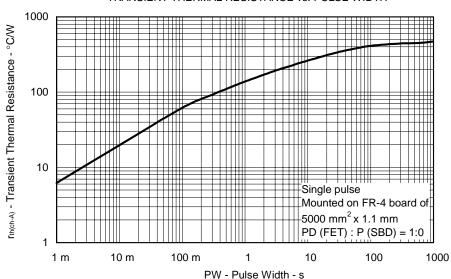




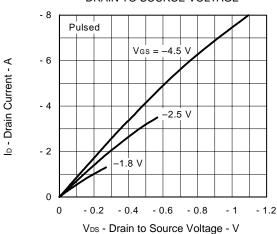
FORWARD BIAS SAFE OPERATING AREA



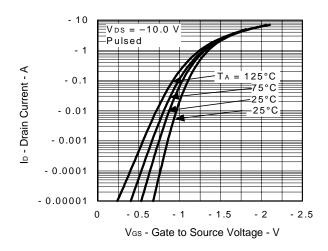
TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



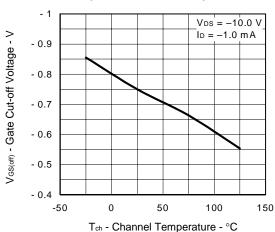
DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE



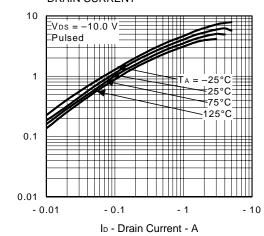
FORWARD TRANSFER CHARACTERISTICS



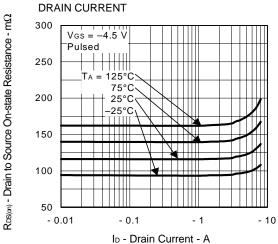
GATE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



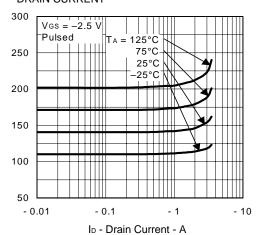
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT



DRAIN TO SOURCE ON-STATE RESISTANCE vs.



DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



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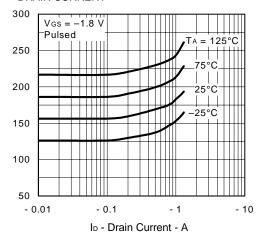
| y_{fs} | - Forward Transfer Admittance

 $\mathsf{R}_{\mathsf{DS}(m)}$ - Drain to Source On-state Resistance - m Ω

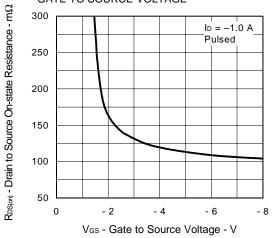
RDS(m) - Drain to Source On-state Resistance - m\Omega

R_{DS(m)} - Drain to Source On-state Resistance - mΩ

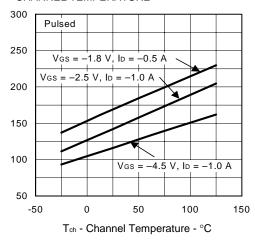
DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



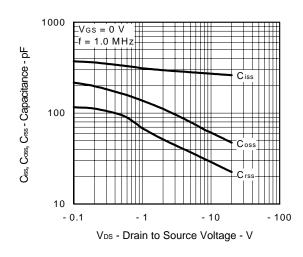
DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



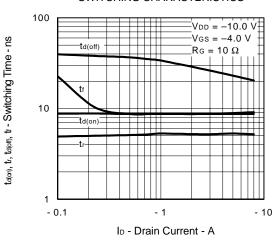
DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



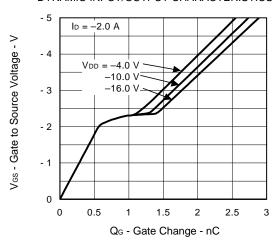
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

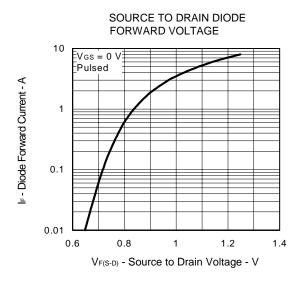


SWITCHING CHARACTERISTICS

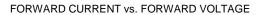


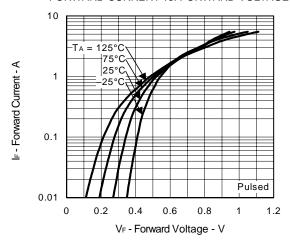
DYNAMIC INPUT/OUTPUT CHARACTERISTICS



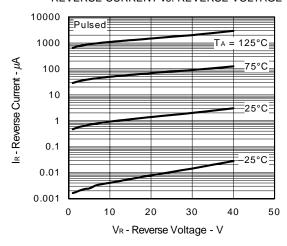


SCHOTTKY BARRIER DIODE TYPICAL CHARACTERISTICS (TA = 25°C)

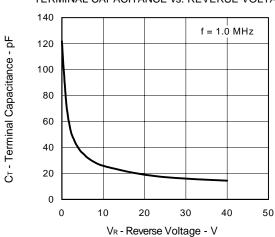




REVERSE CURRENT vs. REVERSE VOLTAGE



TERMINAL CAPACITANCE vs. REVERSE VOLTAGE



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